



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

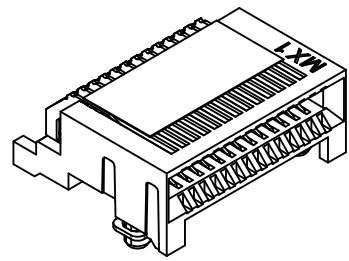
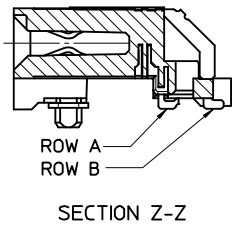
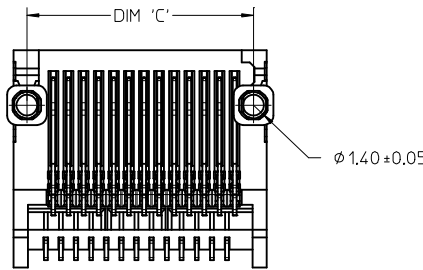
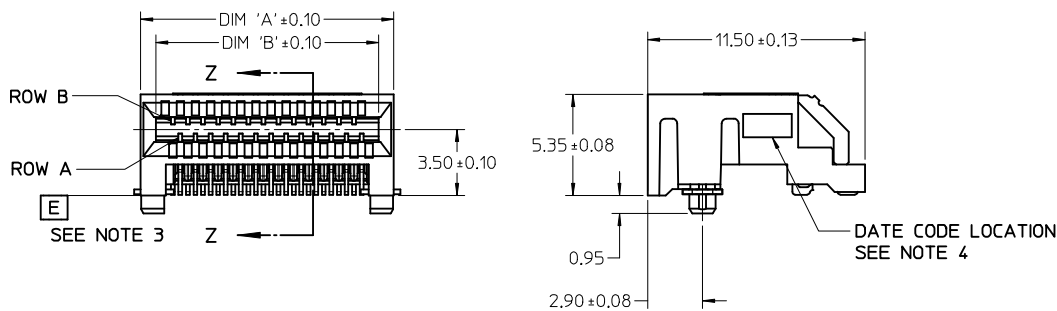
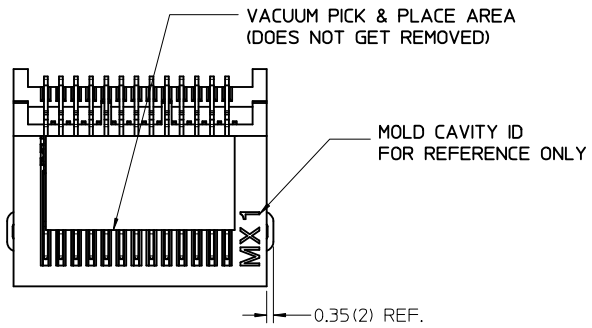
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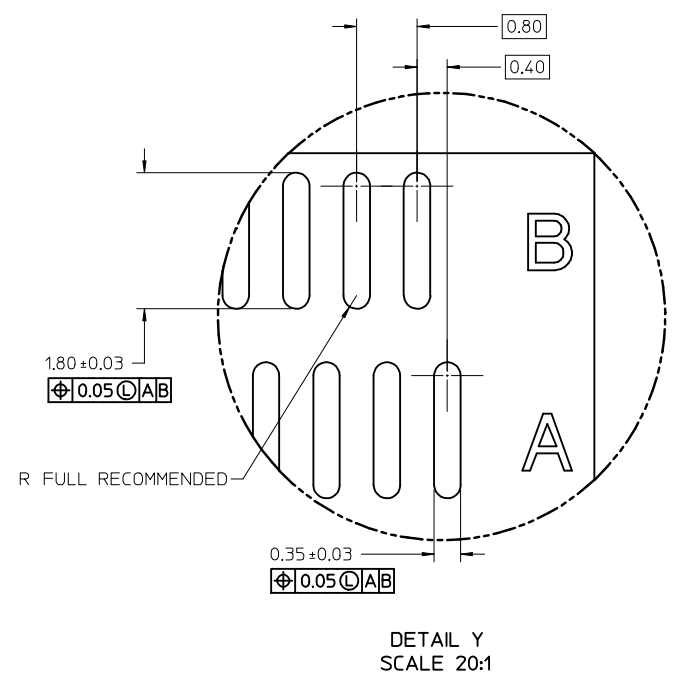
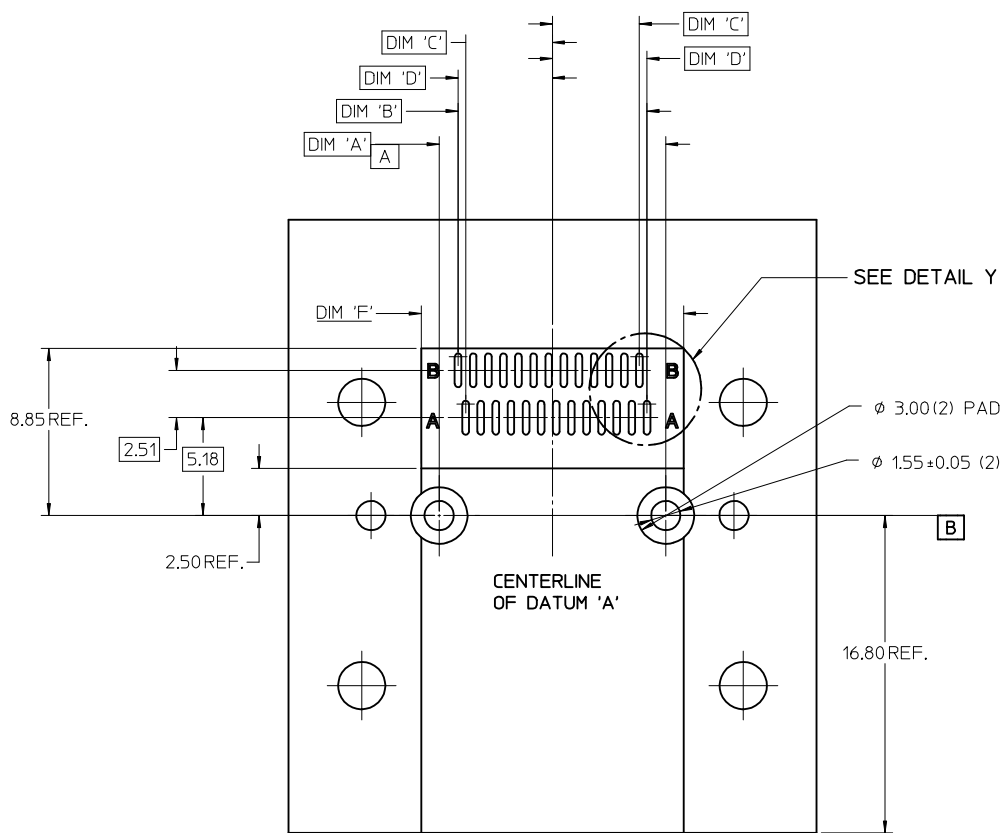
CIRCUIT SIZE	ITEM NUMBER	PLATING OPTION	DIM 'A'	DIM 'B'	DIM 'C'
26	75586-0101	OPTION 1	13.40	11.80	12.00
26	75586-0102	OPTION 2	13.40	11.80	12.00
38	75586-0103	OPTION 1	18.20	16.60	16.80
38	75586-0104	OPTION 2	18.20	16.60	16.80
68	75586-0105	OPTION 1	30.20	28.60	28.80
68	75586-0106	OPTION 2	30.20	28.60	28.80



- NOTES
- MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0, BLACK
TERMINALS - COPPER ALLOY
 - PLATING:
OPTION 1
CONTACT AREA - 0.38 μm MIN GOLD OVER 2.54 μm MIN NICKEL
SOLDER FOOT AREA - 2.54 - 5.09 μm TIN OVER 1.27 μm MIN NICKEL.
OPTION 2
CONTACT AREA - 0.76 μm MIN GOLD OVER 2.54 μm NICKEL
SOLDER AREA - 2.54 - 5.09 μm TIN OVER 1.27 μm MIN NICKEL.
 - TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/004 MEASURED FROM FRONT HOUSING STAND OFF (DATUM E)
 - DATE CODE: 4 DIGIT (3 DIGIT DATE, 1 DIGIT YEAR)
 - CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1
 - TO BE USED WITH EXTERNAL CABLES (74546 & 74547 SERIES) AND GUIDE FRAMES (74540 & 74548 SERIES)
 - TESTER/ANALYZER CABLES AVAILABLE (74557 & 74558 SERIES)
 - PACKAGED PER PACKAGING SPECIFICATION: PK-75586-002
 - CONFORMS TO PRODUCT SPECIFICATION: PS-75586-001
 - THIS PART CONFORMS TO CLASS C REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

REV NOTE 2 IEC NO: UCP2015-0453 DRW:KINGHAM 2014/07/31 CHKD:MCLELLAND 2014/08/01 APPR:MCLELL 2014/08/01	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	▽=0	mm INCH	DRAWN BY DATE KLANG 12/06/2006	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING		DOCUMENT NO. SD-75586-005 SHEET NO. 1 OF 6
	▽=0	4 PLACES ± --- ± ---	CHECKED BY DATE JSWENSON 12/06/2006	MATERIAL NO. SEE CHART		
	▽=0	3 PLACES ± --- ± ---	APPROVED BY DATE MBANAKIS 12/06/2006			
	2 PLACES ± 0.13 ± ---					
		1 PLACE ± 0.25 ± ---				
		0 PLACE ± ±				
		ANGULAR ±1/2°				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				

MOTHERBOARD FOOTPRINT RECOMMENDATION

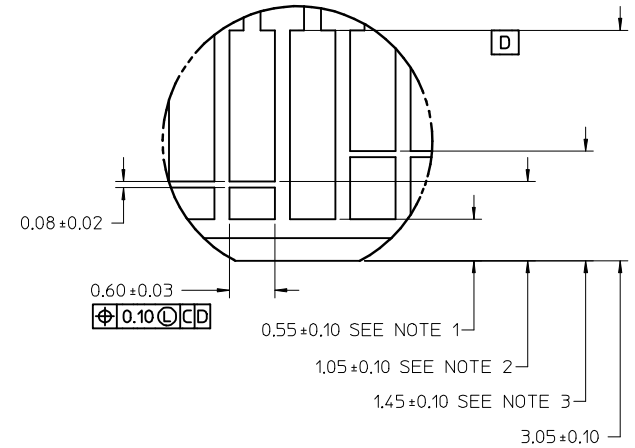
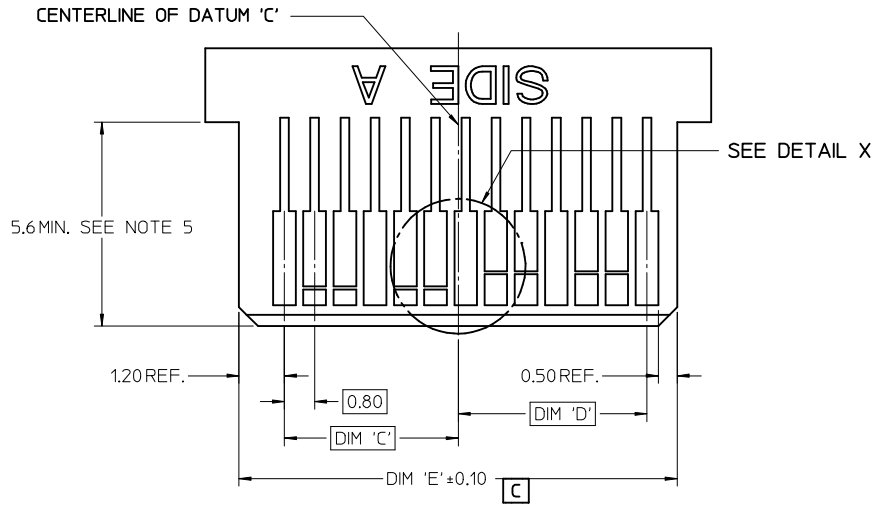


NOTES:
 1. SEE 74540 OR 74548 SERIES FOR GUIDE FRAME FOOT PRINT AND KEEP OUT AREA.

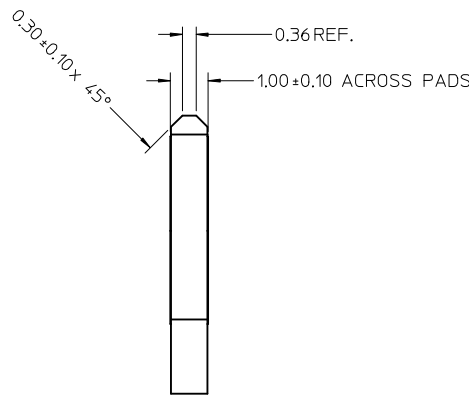
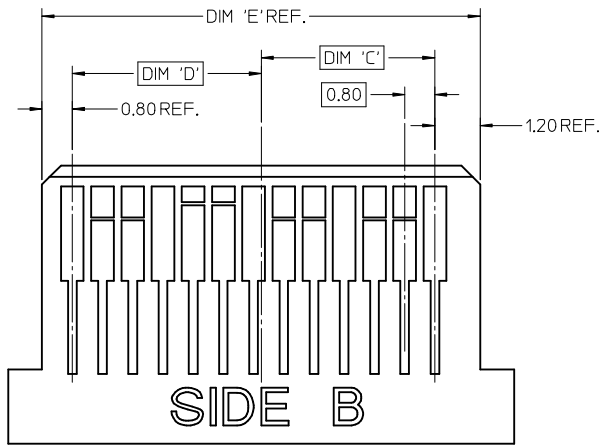
CIRCUIT SIZE	TERM/SIDE 'N'	DIMENSIONS					
		PEG TO PEG	FIRST PAD TO LAST PAD	CENTERLINE TO PAD	CENTERLINE TO PAD	MODULE BOARD WIDTH	CONNECTOR WIDTH
		DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'
26	13	12.00	10.00	4.60	5.00	11.60	13.90
38	19	16.80	14.80	7.00	7.40	16.40	18.70
68	34	28.80	26.80	13.00	13.40	28.40	30.70

SEE SHEET 1 EC NO: UCP2015-0453 DRWING: INGRAM 2014/07/31 CHKD: MCCLELLAND 2014/08/01 APPR: MCCLELL 2014/08/01	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM ONLY	10:1	METRIC	
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE			IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex DOCUMENT NO. SD-75586-005 SHEET NO. 2 OF 6
	▽=0	3 PLACES ± --- ± ---	CHECKED BY DATE			
▽=0	2 PLACES ± 0.13 ± ---	APPROVED BY DATE				
	1 PLACE ± 0.25 ± ---	MATERIAL NO.				
		0 PLACE ± ±	SEE CHART			
		ANGULAR ±1/2°				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				

MODULE BOARD FOOTPRINT RECOMMENDATION



DETAIL X
SCALE 20:1



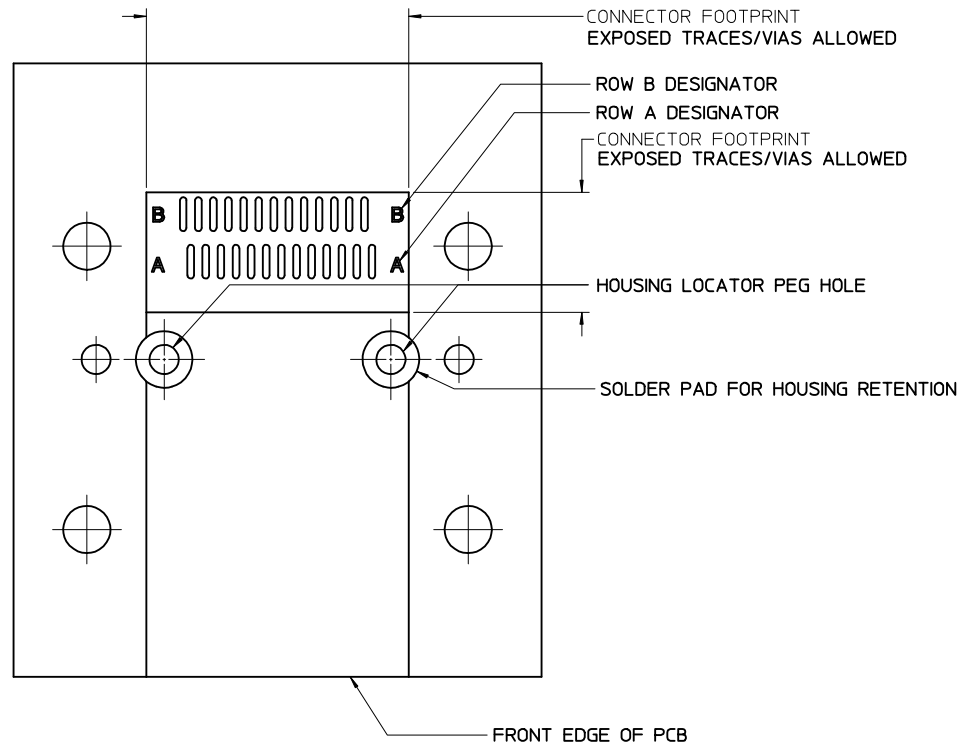
NOTES:

1. PAD CONFIGURATION FOR FIRST MATE.
2. PAD CONFIGURATION FOR SECOND MATE.
3. PAD CONFIGURATION FOR THIRD MATE (HIGH SPEED SIGNALS).
4. FOR PIN ASSIGNMENTS AND MATING SEQUENCE (1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION.
5. MINIMUM STEP REQUIRED IF PCB MADE WIDER THAN CARD TONGUE.

CIRCUIT SIZE	TERM/SIDE 'N'	MODULE BOARD WIDTH		
		CENTERLINE TO PAD	CENTERLINE TO PAD	MODULE BOARD WIDTH
		DIM 'C'	DIM 'D'	DIM 'E'
26	13	4.60	5.00	11.60
38	19	7.00	7.40	16.40
68	34	13.00	13.40	28.40

REV	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
			mm	INCH				
C2	SEE SHEET 1 EC NO: UCP2015-0453 DRAWN: BINGHAM 2014/07/31 CHKD: MCCLELLAND 2014/08/01 APPR: MCCLELL 2014/08/01		4 PLACES ± --- ± ---	KLANG	DRAWN BY DATE 12/06/2006	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING	DOCUMENT NO. SD-75586-005	SHEET NO. 3 OF 6
			3 PLACES ± --- ± ---	CHECKED BY DATE JSWENSON 12/06/2006				
			2 PLACES ± 0.13 ± ---	APPROVED BY DATE MBANAK I S 12/06/2006	SEE CHART			
			1 PLACE ± 0.25 ± ---					
			0 PLACE ± ±					
			ANGULAR ± 1/2°					
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

CONNECTOR FOOTPRINT ZONE IDENTIFICATION



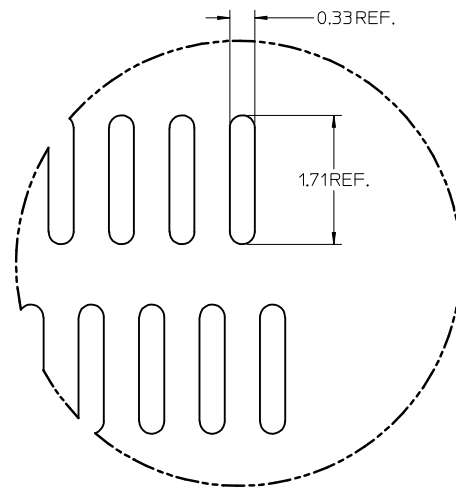
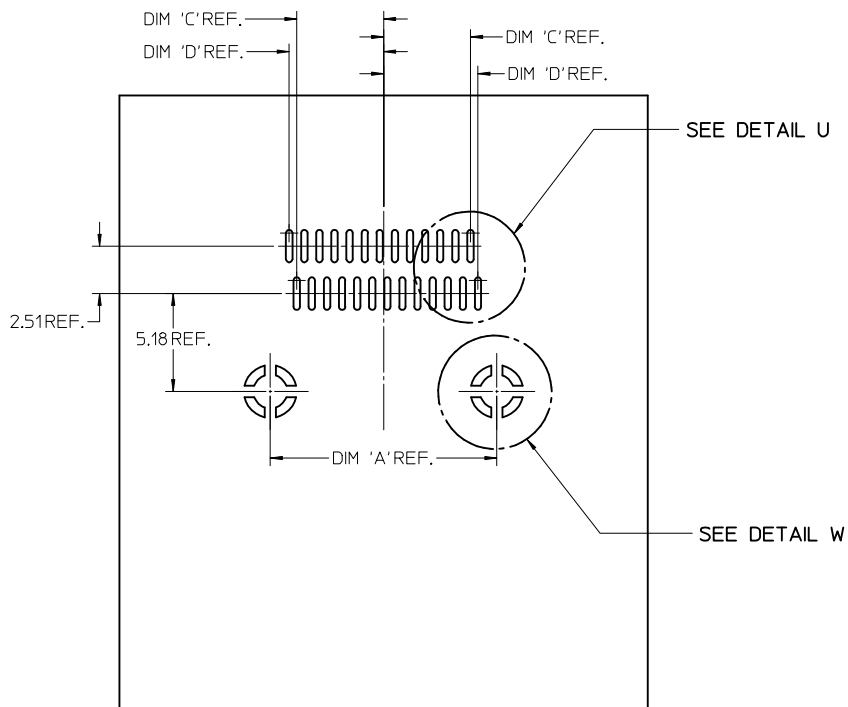
SEE SHEET 1 EC NO: UCP2015-0453 DRW:KINGHAM 2014/07/31 CHKD:MCLELLAND 2014/08/01 APPR:MCLELL 2014/08/01	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm	INCH	MM ONLY	5:1	METRIC	
	▽=0	4 PLACES ± ---	± ---	DRAWN BY	DATE	TITLE	
	▽=0	3 PLACES ± ---	± ---	KLANG	12/06/2006	IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING	
	2 PLACES ± 0.13	± ---	CHECKED BY	DATE	molex DOCUMENT NO. SD-75586-005 SHEET NO. 4 OF 6		
	1 PLACE ± 0.25	± ---	JSWENSON	12/06/2006			
	0 PLACE ±	±	APPROVED BY	DATE			
			MBANAK I S	12/06/2006			
			ANGULAR ±1/2°				
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
C2	REV			SEE CHART			

NOTES:

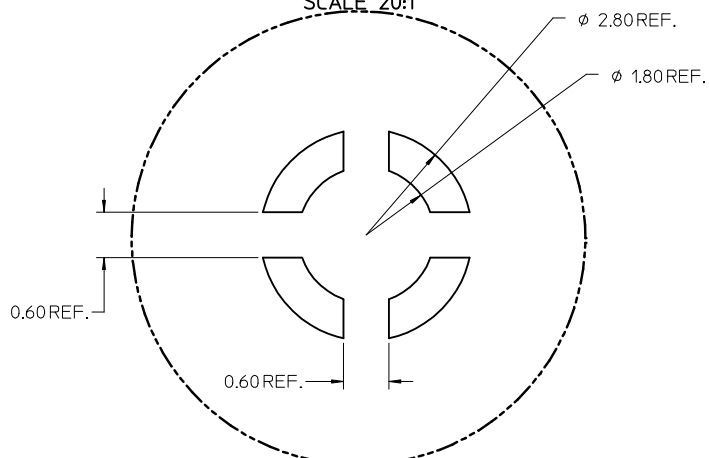
1. STENCIL RECOMMENDATION IS A GUIDELINE ONLY.
2. MANUFACTURING PROCESS PARAMETERS WILL DEFINE THE ACTUAL STENCIL DEFINITION.
3. RECOMMENDED STENCIL THICKNESS IS 0.13MM.

SOLDER STENCIL RECOMMENDATION

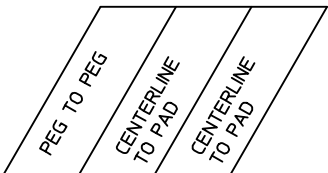
SOLDER FOOT: ~90% OF PAD
 SOLDER RING: ~45% OF PAD



DETAIL U
SCALE 20:1



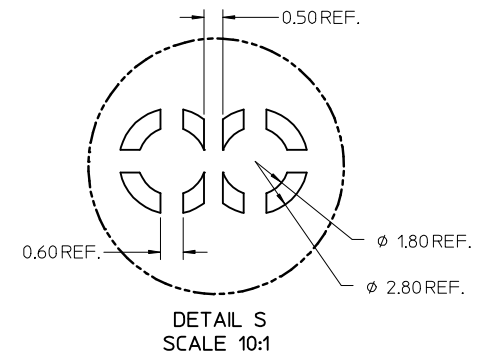
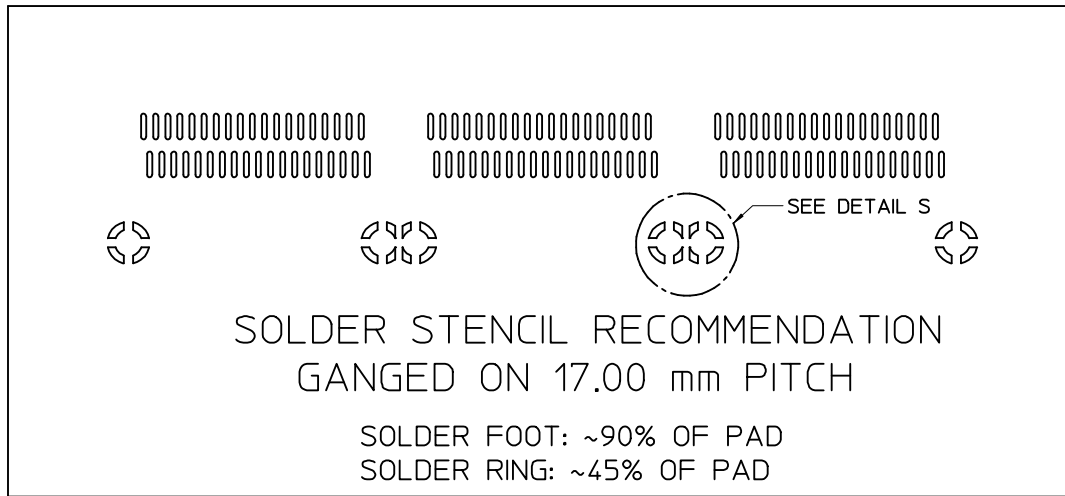
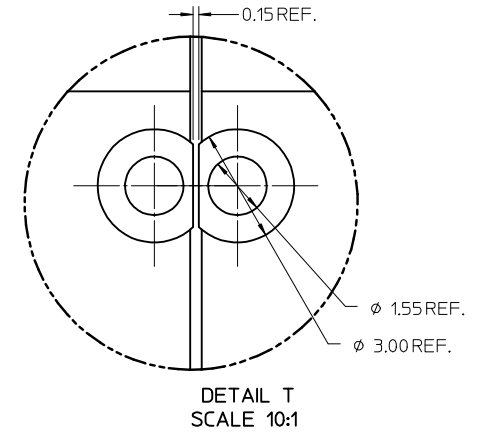
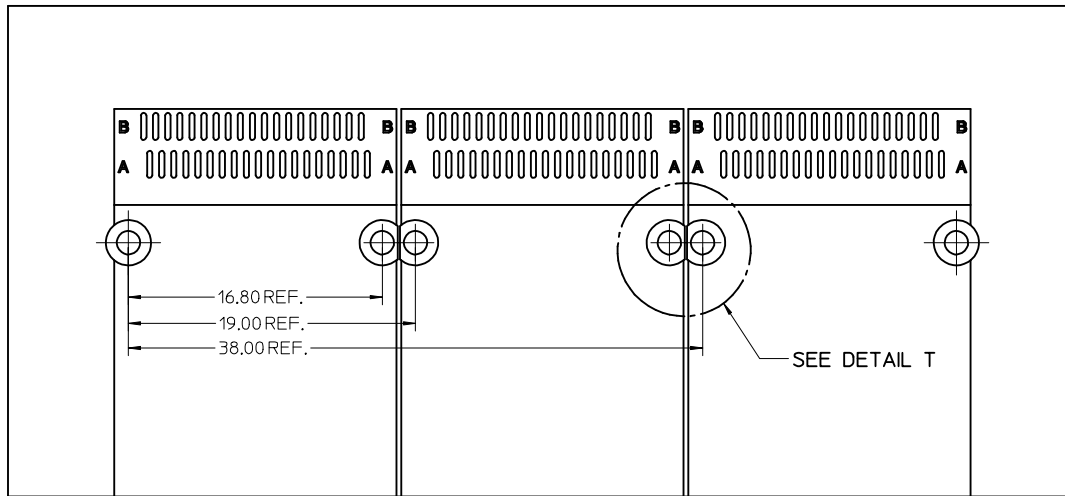
DETAIL W
SCALE 20:1



CIRCUIT SIZE	TERM/SIDE 'N'	DIM 'A'	DIM 'C'	DIM 'D'
26	13	12.00	4.60	5.00
38	19	16.80	7.00	7.40
68	34	26.80	13.00	13.40

SEE SHEET 1 EC NO: UCP2015-0453 DRAWN BY: DRWINGBINGHAM 2014/07/31 CHKD: MCLELLAND 2014/08/01 APPR: MCLELL 2014/08/01	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	▽=0	mm INCH	DRAWN BY DATE KLANG 12/06/2006	TITLE	IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex DOCUMENT NO. SD-75586-005 SHEET NO. 5 OF 6	
	▽=0	4 PLACES ± --- ± ---	CHECKED BY DATE JSWENSON 12/06/2006			
	▽=0	3 PLACES ± --- ± ---	APPROVED BY DATE MBANAK I S 12/06/2006			
	2 PLACES ± 0.13 ± ---	MATERIAL NO.				
	1 PLACE ± 0.25 ± ---	ANGULAR ±1/2°	SEE CHART			
	0 PLACE ± ±	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

38 CIRCUIT GANGED ON 19.00 mm CENTERLINE



NOTES:

1. STENCIL RECOMMENDATION IS A GUIDELINE ONLY.
2. MANUFACTURING PROCESS PARAMETERS WILL DEFINE THE ACTUAL STENCIL DEFINITION.
3. RECOMMENDED STENCIL THICKNESS IS 0.13MM.

SEE SHEET 1 EC NO: UCP2015-0453 DRAWN BY: DRINKBINGHAM 2014/07/31 CHKD: MCCLELLAND 2014/08/01 APPR: MCCLELL 2014/08/01	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY KLANG	DATE 12/06/2006	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING			
4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.13 ± ---	1 PLACE ± 0.25 ± ---	CHECKED BY JSWENSON	DATE 12/06/2006	DOCUMENT NO. SD-75586-005			
0 PLACE ± ±	ANGULAR ±1/2°		MATERIAL NO.		DATE 12/06/2006		SHEET NO. 6 OF 6		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					